

RKR0503BKH

Silicon Schottky Barrier Diode for Rectifying

REJ03G1741-0100

Rev.1.00

Nov 17, 2008

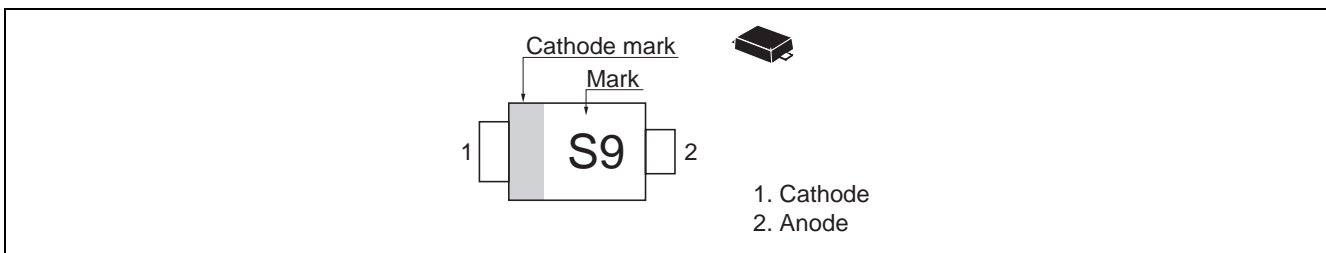
Features

- Low reverse current drop and suitable for high efficiency rectifying.
- Thin Ultra small Resin Package (TURP) is suitable for compact and high-density surface mount design.

Ordering Information

Part No.	Laser Mark	Package Name	Package Code
RKR0503BKH	S9	TURP	PUSF0002ZC-A

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Reverse voltage	V_R	30	V
Average rectified current	$I_O^{*1 *2}$	0.5	A
Non-Repetitive peak forward surge current	I_{FSM}^{*3}	1	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

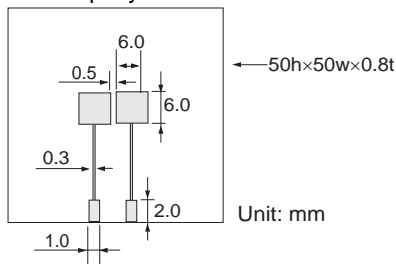
- Notes: 1. See from Fig.6 with Glass epoxy board.
 2. Ta = 63°C, With Glass epoxy board (board size: 50 mm × 50 mm, Land size 6 mm × 6 mm)
 Short form wave (θ180°C), $V_R = 15 V$.
 3. 10 ms sine wave 1 pulse.

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_{F1}	—	—	0.34	V	$I_F = 100 mA$
	V_{F2}	—	—	0.44	V	$I_F = 500 mA$
Reverse current	I_R	—	—	100	μA	$V_R = 30 V$
Thermal resistance	$R_{th(j-a)}$	—	200	—	°C/W	Glass epoxy board *1

- Notes: 1. Glass epoxy board



3. TURP is the structure which radiates heat to a substrate, please perform mounting to a substrate by reflow.

Main Characteristics

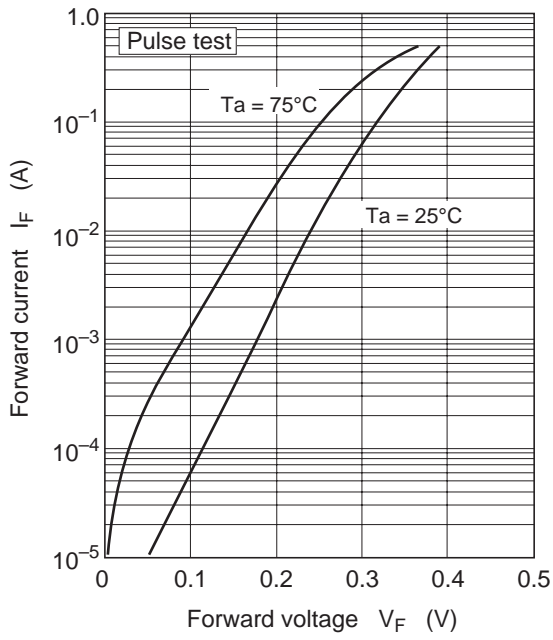


Fig.1 Forward current vs. Forward voltage

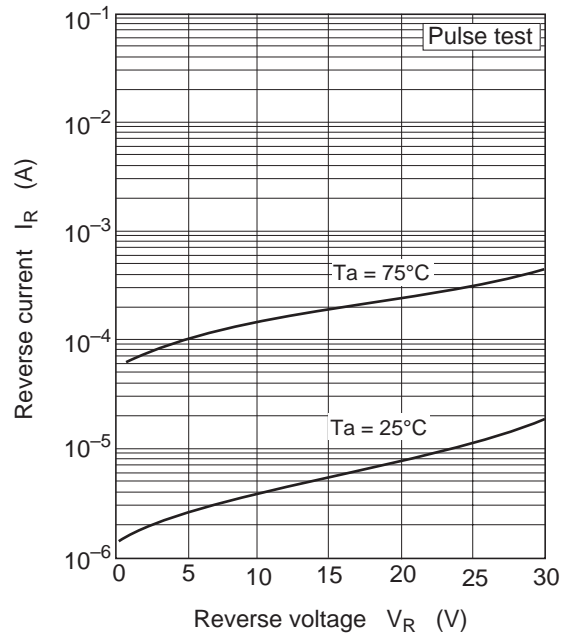


Fig.2 Reverse current vs. Reverse voltage

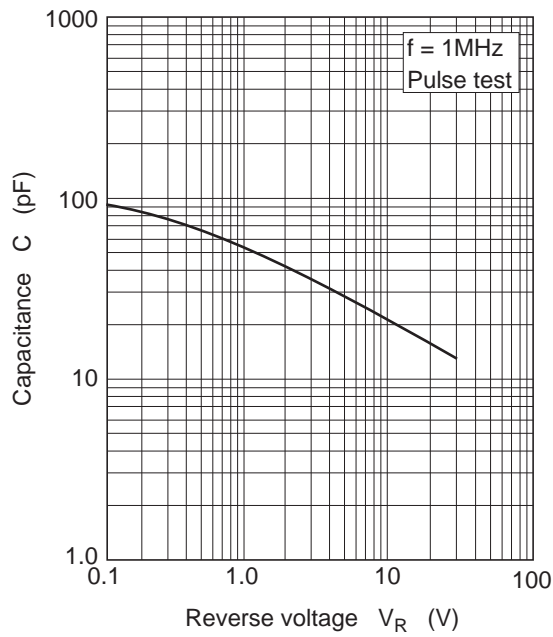


Fig.3 Capacitance vs. Reverse voltage

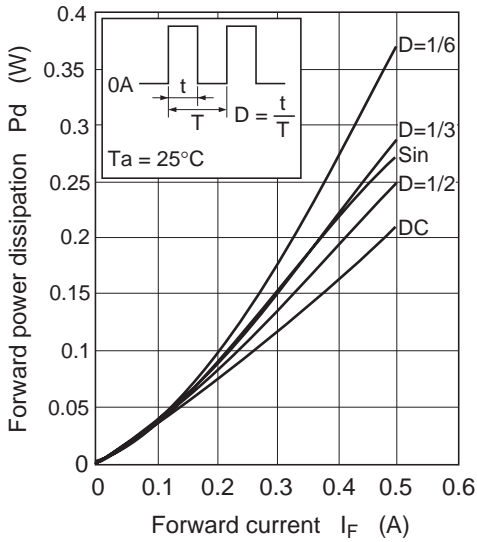


Fig.4 Forward power dissipation vs. Forward current

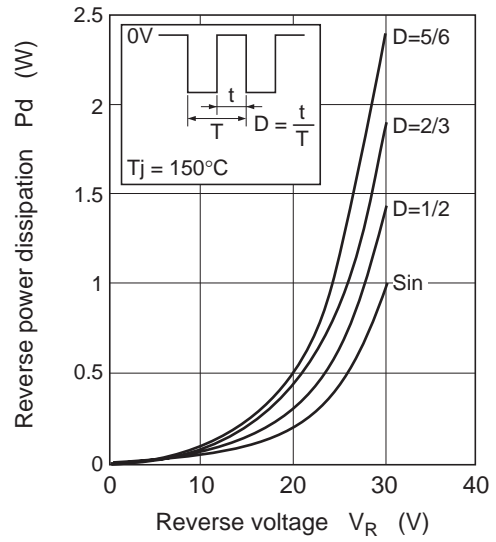


Fig.5 Reverse power dissipation vs. Reverse voltage

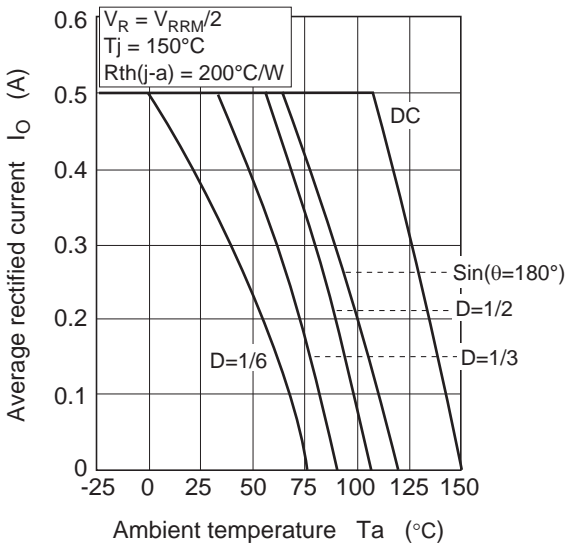
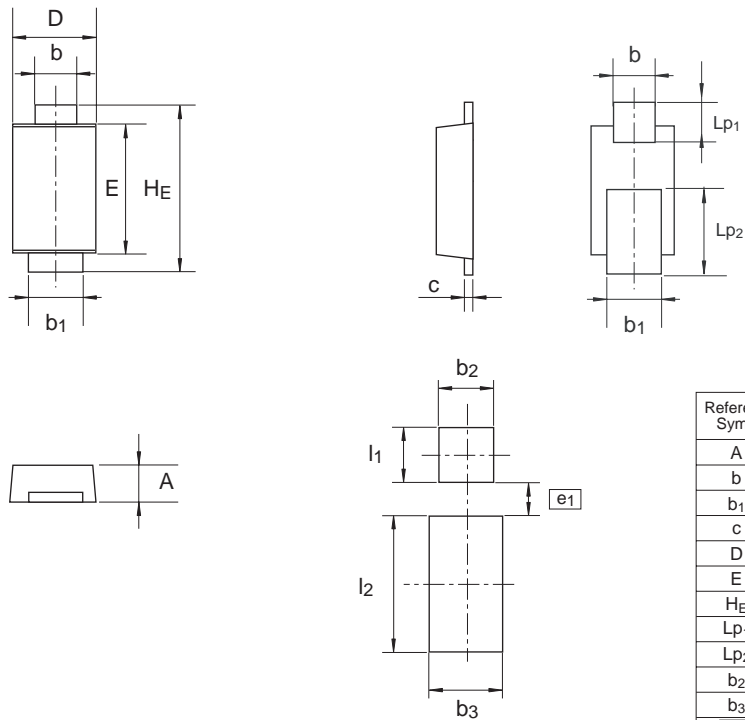


Fig.6 Average rectified current vs. Ambient temperature

Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
TURP	—	PUSF0002ZC-A	TURP/TURPV	0.004g



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	—	—	0.55
b	0.55	0.60	0.65
b1	0.75	0.80	0.85
c	0.08	0.13	0.18
D	1.15	1.25	1.45
E	1.80	1.90	2.00
HE	2.40	2.50	2.60
Lp1	0.40	0.50	0.60
Lp2	1.30	1.40	1.50
b2	—	0.8	—
b3	—	1.1	—
e1	—	0.5	—
l1	—	0.8	—
l2	—	2.0	—

Pattern of terminal position areas

Notes:

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